

2009 CASPA BIMS Delegation Reports

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Led by the president and chairman of CASPA, Jason Wang (王学军), and the head of the CASPA international delegation, Xianfeng Ding (丁险峰), CASPA 2009 BIMS delegation successfully participated 2009 Beijing International Microelectronics Symposium (BIMS, 北京国际微电子研讨会), visited a few important organizations in Beijing and Tianjin.

2009 BIMS is the 10th BIMM event that CASPA co-organized with our Beijing host, BIMS is known to be a good platform for exchanging prospects from important players in the microelectronics industrials, from governmental, multinational and domestic industrial players, experts of major semiconductor associations around the world, and it is quite important that major decision makers come together to share the changing nature of the industrial.

During the dinner reception hosted by Hai Feng, President of the Beijing Semiconductor Association, CASPA's old friend Sheng Liang, vice chairman of Beijing Municipal Commission of Economic and Information Technology (北京经济和信息化委员会), made memorable remarks. Among them, he challenged that since China is where the global semiconductor growth is, Beijing is where CASPA can have most impact to China, and therefore CASPA should have a leader from Beijing to grow CASPA into a semiconductor association with global impacts.

CASPA successfully hosted a special Merge and Acquisition (M&A) session in 2009 BIMS. The session was moderated by Po Chi Wu, a Silicon Valley venture capitalist and executive director of Beijing University Global Innovation Research Center. Six CASPA delegation members presented their own unique professional aspects and case studies of M&A in the US. They are Jim Wu of JW Law group, Jon Rortveit of Tynax, Lam Truong of ZS Dragon, Lung Chu of Global Unichip, John Chin of MoSys, Ching Hu of CASPA director, covering aspects of IP for growth and valuation creation, IP due diligence in cross board transaction, technology M&A in the US market, emergent trend and valuation creation in the consolidated semiconductor eco-system, challenge to harvest the value of the M&A, and M&A during the uncertain period, etc.

CASPA delegation made a few stops in Beijing to explore potential collaborations with different organizations. At Beijing Investment Promotion Bureau (北京投资促进局), the delegation was impressed (as explained by Xinmin Zhang) by the aggressive steps Beijing government took in M&A early this year in auto electronics and semiconductors. At All-China Federation of Industrial & Commerce (全国工商联), the delegation was greeted by a group of ten high level officers led by director general Xiaoming Ouyang and Standing Committee Member Zhengyu Zhang. We learned that

CASPA's members interested in energy could find potential partners with China New Energy Chamber of Commerce, and on facilitating the M&A, with International Cooperation Chamber of Commerce. At Zhongguancun Science Park (中关村科技园), the deputy director Dr. Yingqi Xia of Science Park shared a few Zhongguancun stories with the delegation during the round table discussion and the welcome dinner, and each member received two of his books regarding the start-up guide and how overseas returnees' struggles in Zhongguancun.

CASPA delegation then visited TEDA, or Tianjin Economic-Technological Development Area (天津经济开发区), located in the Binhai new district of Tianjin (天津滨海新区). Led by a CASPA's old friend, a semiconductor veteran Di Sheng Ye, a team consists of officials at TEDA Productivity Promotion Center and Investment Promotion Bureau, had extensive round table discussions with the delegation, covering areas such as TEDA's advantages for new venture investment, government incentives in stimulating the R&D and M&A activities. Vice Chairmen Yamin AI of TEDA's administrative bureau hosted a welcome dinner at the rotating restaurant, where everyone enjoyed the beautiful night view of TEDA.



CASPA delegation members at 2009 BIMS



Delegation member with BSIA President Hai Feng after CASPA M&A forum



Round table meeting at Beijing Zhong Guanchun High Tech Park



Visit TEDA at Tianjin